

Title (en)

Hermetic seal cover and manufacturing method thereof

Title (de)

Hermetischer Deckel und seine Herstellung

Title (fr)

Couvercle à fermeture hermétique et son procédé de fabrication

Publication

**EP 1610380 B1 20100331 (EN)**

Application

**EP 05253109 A 20050519**

Priority

JP 2004181968 A 20040621

Abstract (en)

[origin: EP1610380A2] A hermetic seal cover capable of inhibiting defects such as voids from generating in sealing a package, and a method of manufacturing the seal cover are provided. The hermetic seal cover comprises: a seal cover main body; a Ni plating layer applied onto a surface of the seal cover main body; and a Au-Sn brazing material layer fusion bonded to a surface of the Ni plating layer, and is characterized by a Ni-Sn alloy layer disposed between the Ni plating layer and the Au-Sn brazing material layer. It is preferable if the Ni-Sn alloy layer has a thickness of 0.6-5.0µm. It is also preferable if Au-Sn brazing material layer has a Sn content of 20.65-23.5wt%.

IPC 8 full level

**H01L 23/04** (2006.01); **H01L 21/50** (2006.01); **H01L 23/10** (2006.01)

CPC (source: EP US)

**H01L 23/10** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US)

Designated contracting state (EPC)

CH DE FR GB IT LI

DOCDB simple family (publication)

**EP 1610380 A2 20051228**; **EP 1610380 A3 20070829**; **EP 1610380 B1 20100331**; **EP 1610380 B8 20100526**; DE 602005020216 D1 20100512; JP 2006005262 A 20060105; JP 4285753 B2 20090624; US 2006001172 A1 20060105; US 7495333 B2 20090224

DOCDB simple family (application)

**EP 05253109 A 20050519**; DE 602005020216 T 20050519; JP 2004181968 A 20040621; US 12449805 A 20050506